

ABSTRACT OF THE DISCLOSURE

An electronic device includes: a substrate on which an interconnect pattern is formed; a chip component having a first surface on which a pad is formed and a second surface opposite to the first surface, the chip component being mounted in such a manner that the second surface faces the substrate; a metal layer formed on the pad, the metal layer being less oxidizable than the pad; an insulating section formed of resin adjacent to the chip component; and an interconnect which is formed to extend from above the metal layer, over the insulating section and to above the interconnect pattern.